HETTERO EPTTAXIALLY CROWING METTHOD

HETTERO EPITAXIALLY GROWING METHOD

Patent Number:

JP5182906

Publication date:

1993-07-23

inventor(s):

NAKAJIMA HISAO; others: 06

Applicant(s):

SUMITOMO ELECTRIC IND LTD

Requested Patent:

JP5182906

Application Number: JP19910346646 19911227

Priority Number(s):

IPC Classification:

H01L21/20; C30B23/08; C30B29/42; H01L21/203

EC Classification:

EC Classification:

Equivalents:

Abstract

PURPOSE:To obtain a GaAs epitaxial layer having a low dislocation and high quality by growing a group II element single atomic layer on an As single atomic layer, growing a low temperature GaAs buffer layer thereon and epitaxially growing a GaAs layer on the buffer layer. CONSTITUTION: An Si (100) board 1 is heated to 250 deg.C, and an As single atomic layer 2 is formed thereon. Then, a single atomic layer 3 of group II element such as Zn, Be, Mg, etc., is formed thereon. Thereafter, while a growing temperature remains at 250 deg.C, a low temperature GaAs buffer layer 4 is grown on the layer 3. Then, the growing temperature is raised to 550 deg.C. and a GaAs epitaxial layer 5 is grown. Thus, a two-dimensional grown can be controlled in an initial step of the GaAs epitaxial growth on the board.